







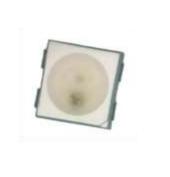




- ► PLCC4 SMD with IC
- ➤ 3535IC 1.47t Series
- ► Red/Green/Blue

N0M45S35IC





3535 IC Integrated

APPLICATIONS:

- Telecommunication
- Indicator
- Home Appliance
- **Decoration Lighting**
- Full Colour LED Strip
- **Gaming Device**







FEATURES:

- Package: PLCC4 EIA STD Package with Integrated IC Type 104
- Forward Current: 5mA
- Forward Voltage (typ.): +3.8~+5.5V
- Luminous Intensity (typ.): 810mcd mixed white
- Colour: Red/Green/Blue
- Wavelength: 622/525/467nm
- Viewing angle: 120°
- **Materials:**
 - Resin: Silicone (White Diffused)
 - L/F Finish: Ag Plated
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+105°C
- IC Feature:

One Pixel contains R, G, and B colour each can achieve 256 level brightness greyscales, which form 16,777,216 combination colours. Internal clock frequency operates at 800kHz. Serial data transmission signal by single wire.

- Soldering methods: IR Reflow soldering
- Preconditioning: acc. to JEDEC Level 3
- Packing: 12mm tape with Max.1300pcs/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	5	mA
IC Power Supply Voltage	V _{DD}	+3.8~+5.5	V
IC Input Voltage	Vı	-0.4~V _{DD} +0.4	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+105	°C

Electrical & Optical Characteristics (Ta=25°C)

Parameter		Symbol	Values			Unit	Test
		Зуппоот	Min.	Тур.	Max.	Offic	Condition
	R		115	170	255		
Luminaus Intensity	G	,	355	530	795	mcd	I⊧=5mA
Luminous Intensity	В	Ιv	80	120	180		
	W		460	810	1700		
	R		615		630		
Dominant Wavelength	G	λ_{D}	520		530	nm	I _F =5mA
	В		460		475		
Colour Coordinate X				0.2170			I _F =5mA
Colour Coordinate	Υ	-		0.2750			IF-SITIA
Viewing Angle		2θ _{1/2}		120		deg	I _F =5mA



Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values			Unit	Test
Parameter	Syllibol	Min.	Тур.	Max.	Onit	Condition
Static Current IDD			0.3		mA	V _{DD} =4.5V
Static Current	IDD		0.5		Ш	I _{OUT} =OFF
Input Voltage Level	V _{IH}	$0.7V_{DD}$			V	D _{IN} , SET
Input Voltage Level	VIL			0.3 V _{DD}	V	D _{IN} , SET

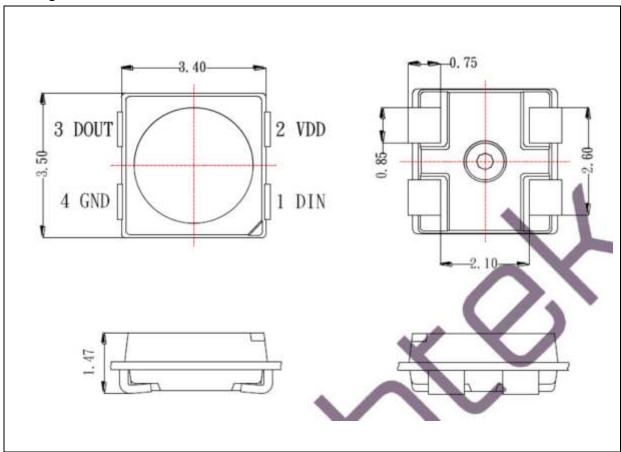
Switching Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition	
- Parameter	Зуппоп	Min.	Тур.	Max.	UIIIL	rest condition	
Rate of Data Signal	F _{DIN}		0.8		MHz		
Transfer Time	T _{PLH}			80	ns	D . D	
Transfer Time	T _{PHL}			80	ns	D _{IN} -> D _{OUT}	
Conversion Time of IOUT R/G/B	Tr			50	ns	I _{OUT} R/G/B=5Ma RL=400Ω	
Conversion time of four K/G/B	Tf			100	ns	CL=15pF	



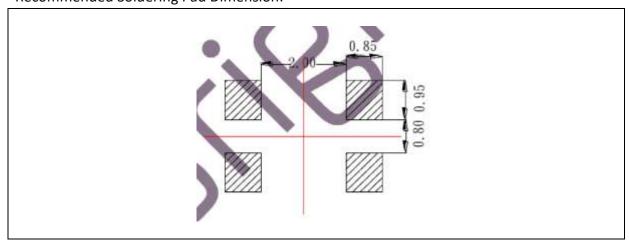
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

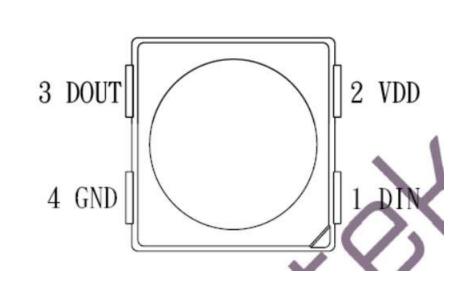
Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



PIN CONFIGURATION:



No.	Symbol	Function Description
1	DIN	Control data signal input
2	VDD	Power Supply LED
3	DOUT	Control data signal output
4	GND	Ground



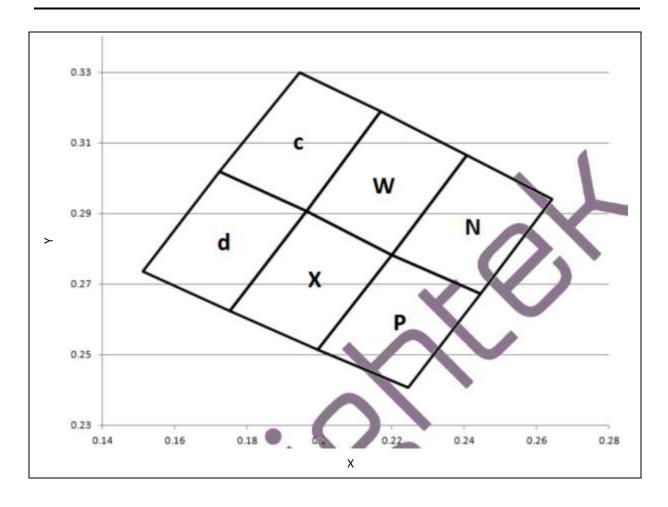
BINNING GROUPS:

Luminous Intensity Classifications (White) ($I_F = 5mA$):

Code	Min.	Max.	Unit
12	460	600	
13	600	780	
14	780	1000	mcd
15	1000	1300	
16	1300	1700	



CIE CHROMATICITY DIAGRAM:



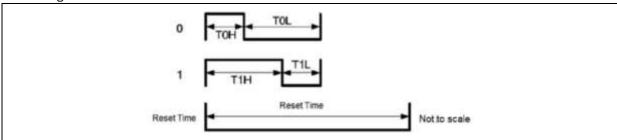
Chromaticity Coordinates Classifications (I_F = 5mA):

	í	1	2		3		4	
	Х	Υ	X	Υ	X	Υ	Х	Υ
С	0.1945	0.3299	0.1723	0.3018	0.1963	0.2907	0.2169	0.3188
D	0.1723	0.3018	0.1512	0.2735	0.1752	0.2624	0.1963	0.2907
N	0.2200	0.2783	0.2406	0.3064	0.2643	0.2940	0.2444	0.2672
Р	0.2200	0.2783	0.1996	0.2513	0.2244	0.2407	0.2444	0.2672
Х	0.1963	0.2907	0.1752	0.2624	0.1996	0.2513	0.2200	0.2783
W	0.1963	0.2907	0.2169	0.3188	0.2406	0.3064	0.2200	0.2783



DATA TRANSFER TIME (TH+TL=1.2μs±600ns):

1. Timing Wave Form



2. High Speed Mode

Item	Description	Typical	Allowance
Тон	0 code, high voltage time	300ns	±150ns
T _{OL}	0 code, low voltage time	900ns	±150ns
Т1н	1 code, high voltage time	900ns	±150ns
T _{1L}	1 code, low voltage time	300ns	±150ns
RES	Reset Time	>200µs	

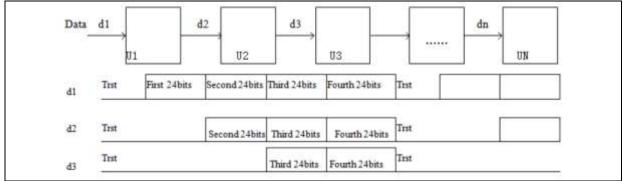
Note:

- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
- 2. $\Theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial intensity.
- 3. The dominant wavelength, λ_d is derived from CIE chromaticity diagram and represents the single wavelength which defines the colour of the device. Peak emission wavelength tolerance is ± 1 nm.

3. Composition of 24 Bit Data



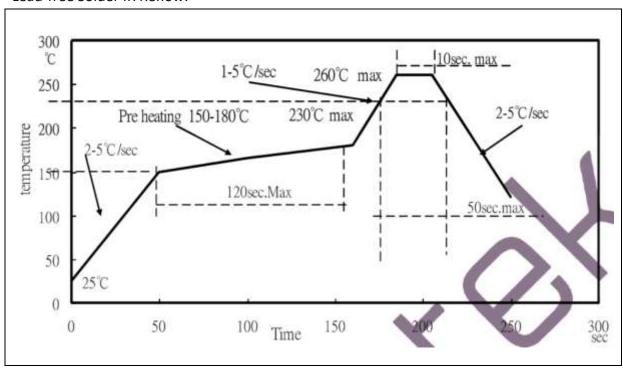
3. Data Transmission Method





RECOMMENDED SOLDERING PROFILE:

Lead-free Solder IR Reflow:



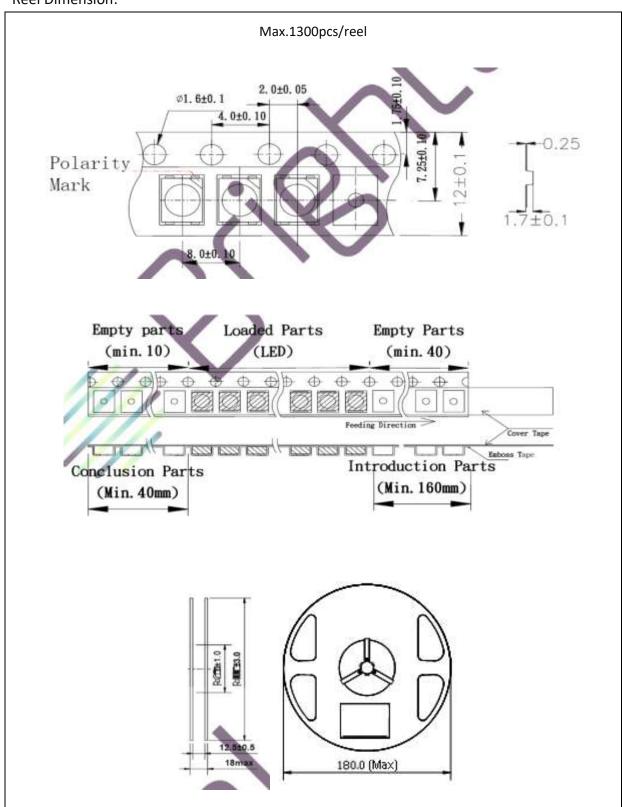
Note:

- 1. We recommend the reflow temperature 245°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 6hrs before use.

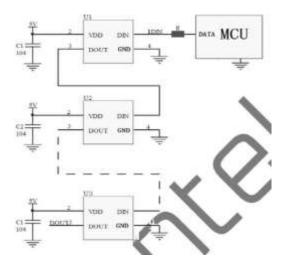
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	17/01/2019	Datasheet set-up.